



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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Parameter	Rating	Units
Breakdown Voltage - BV_{CEO}	30	V_P
Current Transfer Ratio - CTR (typical)	8500	%
Saturation Voltage - $V_{CE(sat)}$	1	V
Input Control Current - I_F	1	mA

Features

- 100mA Continuous Load Rating
- 3750V_{rms} Input/Output Isolation
- Unidirectional Input
- Small 8-Pin Package, Thru-Hole or Surface Mount
- Machine Insertable, Wave Solderable
- Surface Mount Tape & Reel Packaging Available

Applications

- Telecom Switching
- Tip/Ring Circuits
- Modem Switching (Laptop, Notebook, Pocket Size)
- Loop Detect
- Ringing Detect
- Current Sensing

Description

LDA213 is a dual unidirectional-input optocoupler with Darlington-transistor outputs. The LDA213 has a minimum current transfer ratio (CTR) of 300% with a typical value of 8500%.

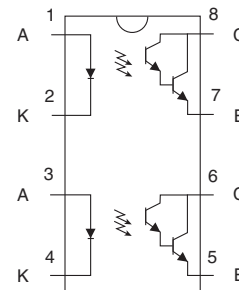
Approvals

- UL Recognized Component: File E76270
- CSA Certified Component: Certificate 1175739
- EN/IEC 60950-1 Certified Component:
TUV Certificate B 09 07 49410 006

Ordering Information

Part Number	Description
LDA213	8-Pin DIP (50/tube)
LDA213S	8-Pin Surface Mount (50/tube)
LDA213STR	8-Pin Surface Mount (1000/Reel)

Pin Configuration



Absolute Maximum Ratings @ 25°C

Parameter	Ratings	Units
Breakdown Voltage	30	V _P
Reverse Input Voltage	5	V
Input Control Current	100	mA
Peak (10ms)	1	A
Power Dissipation		
Input Power Dissipation ¹	150	mW
Phototransistor ²	150	
Isolation Voltage, Input to Output	3750	V _{rms}
Operational Temperature	-40 to +85	°C
Storage Temperature	-40 to +125	°C

¹ Derate linearly 1.33mW / °C

² Derate linearly 2mW / °C

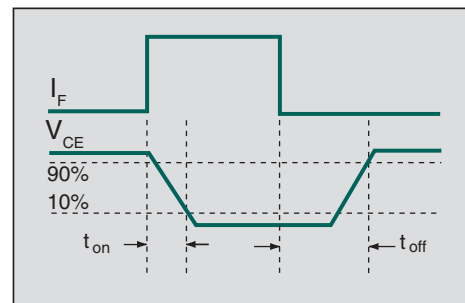
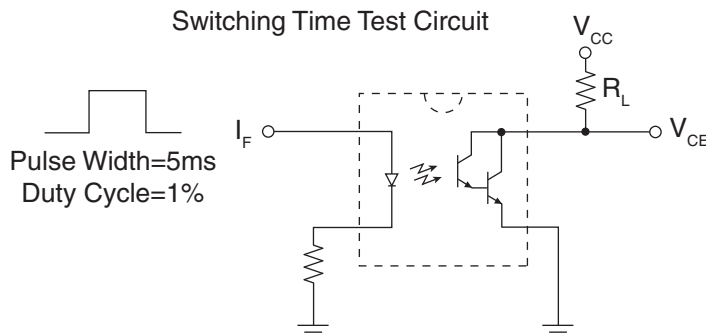
Absolute Maximum Ratings are stress ratings. Stresses in excess of these ratings can cause permanent damage to the device. Functional operation of the device at conditions beyond those indicated in the operational sections of this data sheet is not implied.

Electrical Characteristics @ 25°C

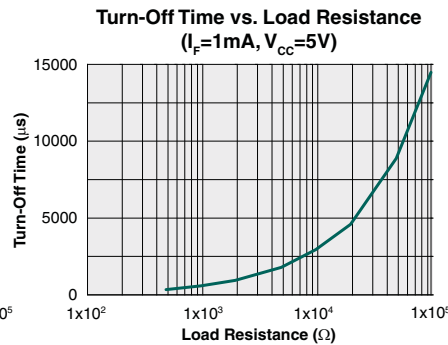
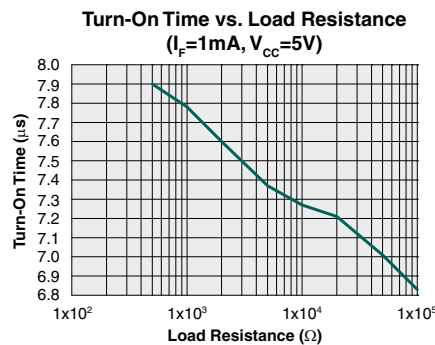
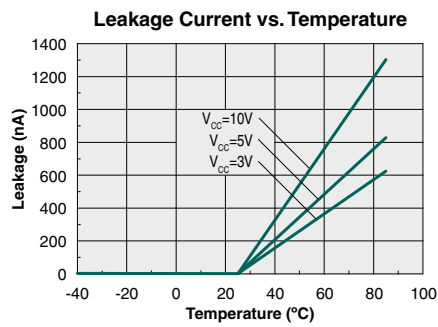
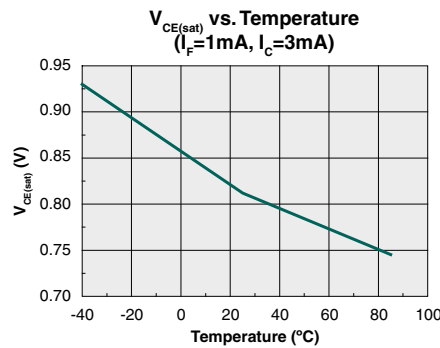
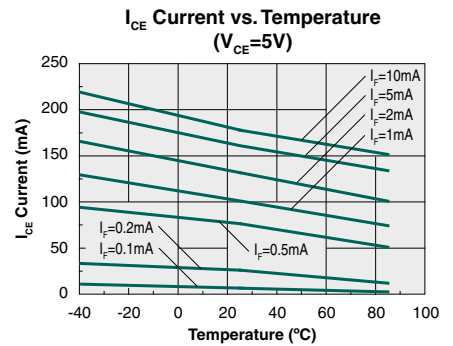
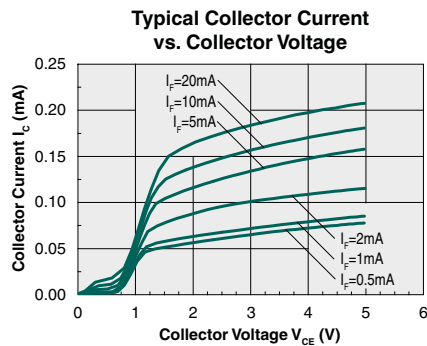
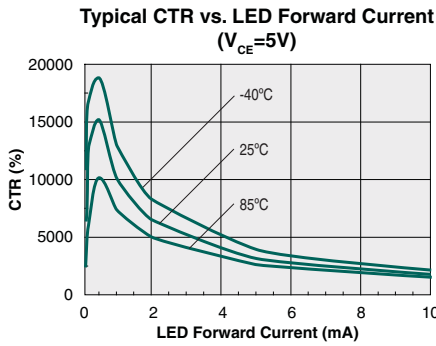
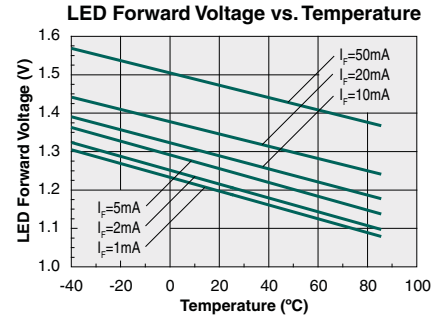
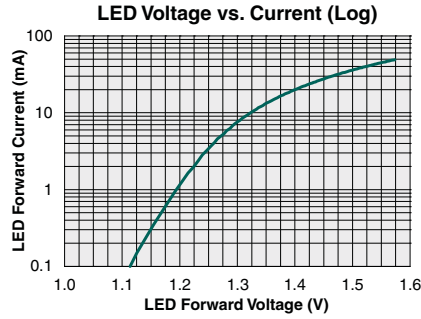
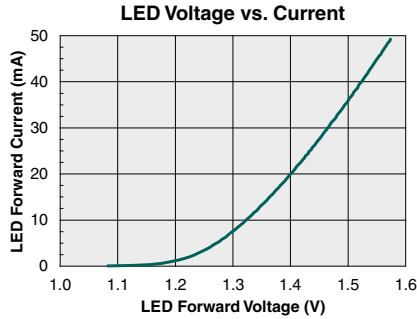
Parameter	Conditions	Symbol	Min	Typ	Max	Units
Output Characteristics						
Phototransistor Breakdown Voltage	I _C = 100µA	BV _{CEO}	30	50	-	V
Phototransistor Dark Current	V _{CEO} = 5V, I _F = 0mA	I _{CEO}	-	50	500	nA
Saturation Voltage	I _C = 3mA, I _F = 1mA	V _{CE(sat)}	-	-	1	V
Current Transfer Ratio	I _F = 1mA, V _{CE} = 2V	CTR	300	8500	30000	%
Output Capacitance	50V, f = 1MHz	C _{OUT}	-	3	-	pF
Input Characteristics						
Input Control Current	I _C = 3mA, V _{CE} = 2V	I _F	-	0.07	1	mA
Input Voltage Drop	I _F = 5mA	V _F	0.9	1.2	1.4	V
Reverse Input Current	V _R = 5V	I _R	-	-	10	µA
Common Characteristics						
Capacitance, Input to Output	-	C _{I/O}	-	3	-	pF

Switching Characteristics @ 25°C

Characteristic	Symbol	Test Condition	Typ	Units
Turn-On Time	t _{on}	V _{CC} =5V, I _F =1mA, R _L =500Ω	8	µs
Turn-Off Time	t _{off}		345	



PERFORMANCE DATA @25°C (Unless Otherwise Noted)*



*The Performance data shown in the graphs above is typical of device performance. For guaranteed parameters not indicated in the written specifications, please contact our application department.

Manufacturing Information

Moisture Sensitivity



All plastic encapsulated semiconductor packages are susceptible to moisture ingress. IXYS Integrated Circuits Division classified all of its plastic encapsulated devices for moisture sensitivity according to the latest version of the joint industry standard, **IPC/JEDEC J-STD-020**, in force at the time of product evaluation. We test all of our products to the maximum conditions set forth in the standard, and guarantee proper operation of our devices when handled according to the limitations and information in that standard as well as to any limitations set forth in the information or standards referenced below.

Failure to adhere to the warnings or limitations as established by the listed specifications could result in reduced product performance, reduction of operable life, and/or reduction of overall reliability.

This product carries a **Moisture Sensitivity Level (MSL) rating** as shown below, and should be handled according to the requirements of the latest version of the joint industry standard **IPC/JEDEC J-STD-033**.

Device	Moisture Sensitivity Level (MSL) Rating
LDA213 / LDA213S	MSL 1

ESD Sensitivity



This product is **ESD Sensitive**, and should be handled according to the industry standard **JESD-625**.

Reflow Profile

This product has a maximum body temperature and time rating as shown below. All other guidelines of **J-STD-020** must be observed.

Device	Maximum Temperature x Time
LDA213 / LDA213S	250°C for 30 seconds

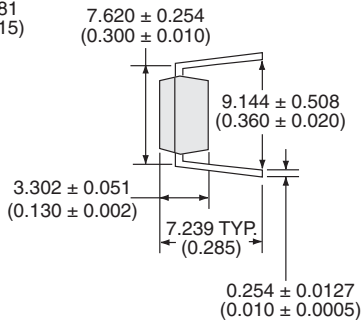
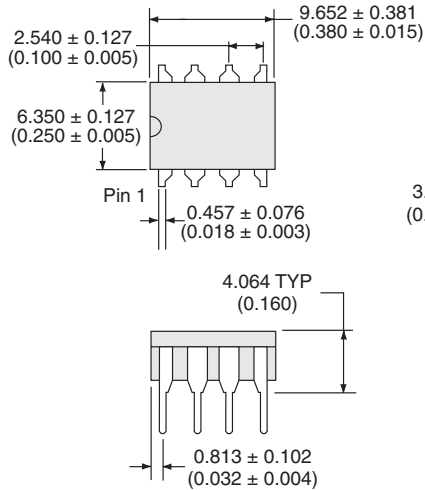
Board Wash

IXYS Integrated Circuits Division recommends the use of no-clean flux formulations. However, board washing to remove flux residue is acceptable. Since IXYS Integrated Circuits Division employs the use of silicone coating as an optical waveguide in many of its optically isolated products, the use of a short drying bake could be necessary if a wash is used after solder reflow processes. Chlorine- or Fluorine-based solvents or fluxes should not be used. Cleaning methods that employ ultrasonic energy should not be used.

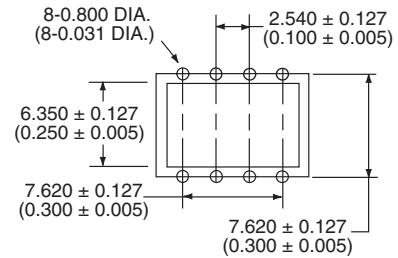


Mechanical Dimensions

LDA213

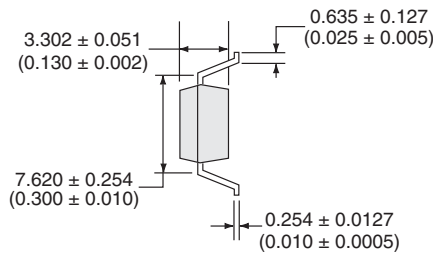
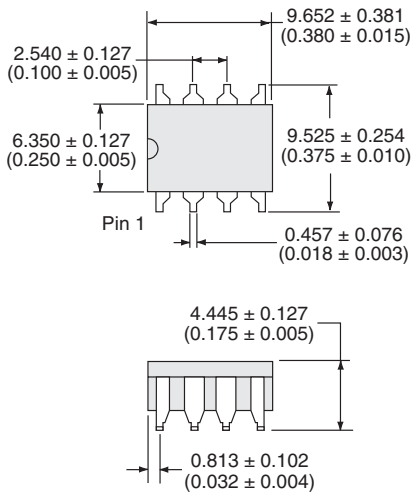


PCB Hole Pattern

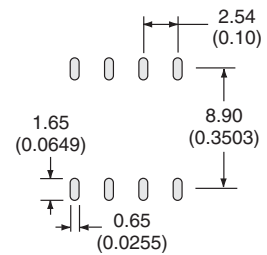


Dimensions
mm
(inches)

LDA213S

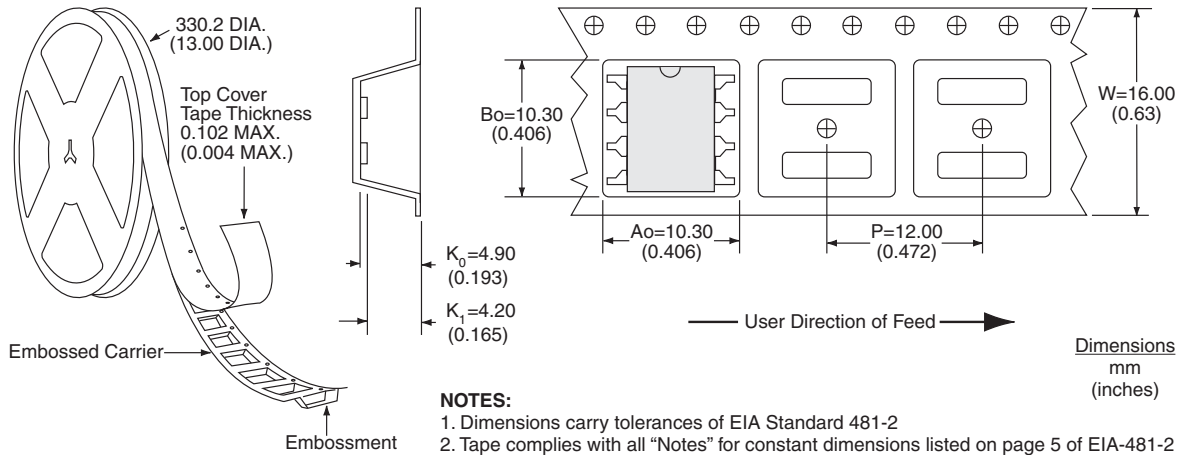


PCB Land Pattern



Dimensions
mm
(inches)

LDA213STR Tape & Reel



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